



SF206B Low Dk/Df 胶膜

SF206B

Low Dk/Df Bonding Film

特点

- 低介电常数，低传输损耗
- 与铜箔和 PI 具有良好的粘结性
- 不含卤素
- 优秀的耐热性、耐化学性和电性能
- 满足 RoHS 指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

FEATURES

- Low dielectric constant, low dissipation loss
- The copper has excellent peel strength with the PI film
- Halogen free
- Good processability, suitable for traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg,Cd, Cr⁶⁺,PBB,PBDE, etc..

应用领域

高频多层印制板和刚挠性多层印制板等用粘接

APPLICATIONS

Be used in high frequency multi-layer FPC and rigid-flex PCB as the bonding lay

性能表 GENERAL PROPERTIES

| 性能项目 Test Item | 测试方法 Test Method | 单位 Unit | IPC 标准值* Standard | 典型值 Typical Value |
|-----------------------------------|---------------------------------|------------|----------------------|----------------------|
| | | | | SF206B 25 |
| 溢胶量 Resin Flow | SY Method | mm | - | <0.15 |
| 剥离强度 Peel Strength (90°) | IPC-TM-650,No.2.4.9 Method A | N/mm | ≥0.7 | 1.1 |
| | Method C | | ≥0.7 | 1.1 |
| 热应力 Thermal Stress | IPC-TM-650,No.2.4.13 | - | Pass | Pass |
| 吸水率 Moisture Absorption | IPC-TM-650,No.2.6.2 | % | ≤1.1 | 0.24 |
| 体积电阻率 Volume Resistivity | IPC-TM-650,No.2.5.17 | MΩ-cm | ≥10 ⁷ | 3.03×10 ⁹ |
| 表面电阻 Surface Resistance | IPC-TM-650,No.2.5.17 | MΩ | ≥10 ⁶ | 1.92×10 ⁶ |
| 介电常数 10GHz Dielectric Constant | SPDR | - | <3.4 | 2.52 |
| 介电损耗 10GHz Dissipation Factor | SPDR | - | ≤0.03 | 0.0026 |

注释 Remarks:* Certified to IPC-4203/24 Unsupport polyimide adhesive



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产品规格代码描述 Product Code Description

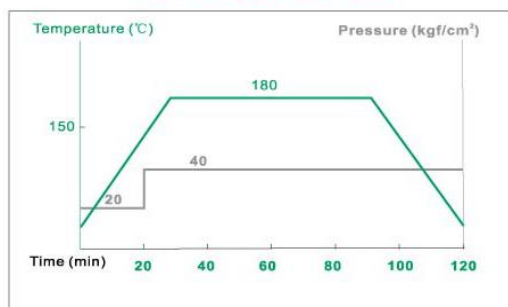
SF206B 25

常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

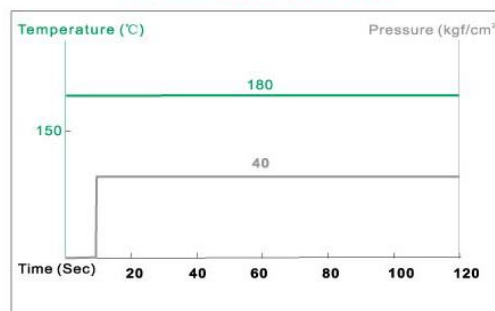
| 产品规格 Specifications | 胶粘剂厚度 Adhesive Thickness (µm) | 应用领域 Applications |
|------------------------|----------------------------------|---|
| SF206B 13 | 13 | 多层板、软硬结合板 Multi-layer FPC and rigid-flex PCB |
| SF206B 25 | 25 | |
| SF206B 40 | 40 | |
| SF206B 50 | 50 | |

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件是 160-180℃ 、90-120 分钟。The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-180℃ for 90-120min.

包装 PURCHASING INFORMATION

产品宽度 250+2/-0mm 或 500+2/-0mm，每卷 100+2/-0 米或 200+2/-0 米；其它规格、尺寸可根据客户要求而定。SF206B is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

贮存条件 STORAGE CONDITION

贮存在干燥、无腐蚀气体的室内。以原始包装贮存在 4-10℃ 的冷藏室里，贮存期为三个月。Stored in dry room with humidity control and with no corrosive gases. Three months when stored in the original packaging at 4-10℃.